

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CB0</sub>	200	V
Collector-Emitter Voltage	V <sub>CEO</sub>	150	V
Emitter-Base Voltage	V <sub>EBO</sub>	7	V
Continuous Collector Current	I <sub>C</sub>	1	A
Peak Pulse Current	I <sub>CM</sub>	3	A
Base Current	I <sub>B</sub>	500	mA

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

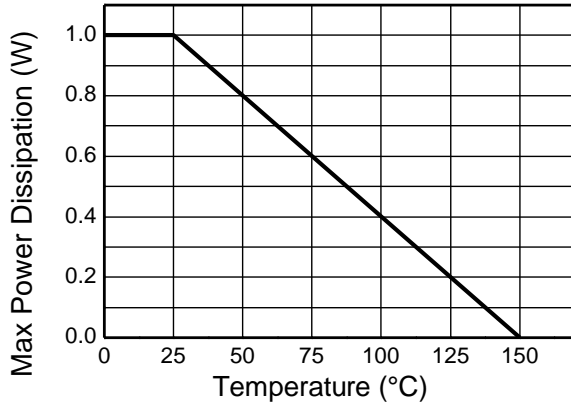
Characteristic	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	(Note 6)	1
		(Note 7)	1.5
		(Note 8)	2.0
Thermal Resistance, Junction to Ambient Air	R <sub>θJA</sub>	(Note 6)	125
		(Note 7)	83
		(Note 8)	60
Thermal Resistance, Junction to Lead	R <sub>θJL</sub>	13	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**ESD Ratings** (Note 10)

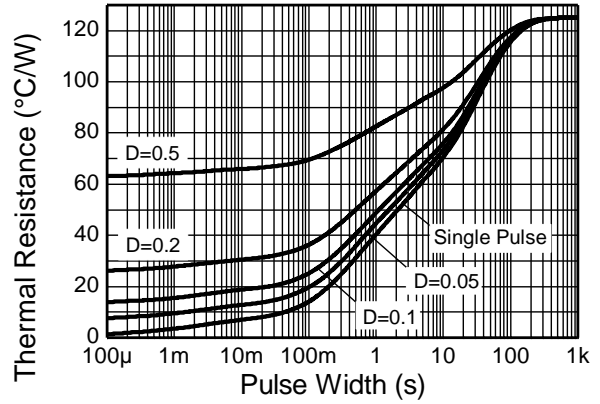
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- 6. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  - 7. Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.
  - 8. Same as Note 6, except the device is mounted on 50mm x 50mm 1oz copper.
  - 9. Thermal resistance from junction to solder-point (on the exposed collector pad).
  - 10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

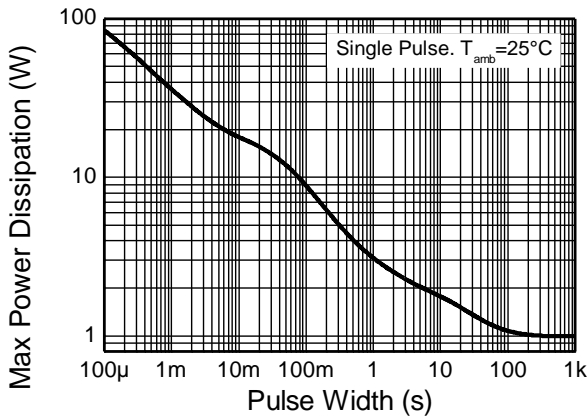
**Thermal Characteristics and Derating Information**



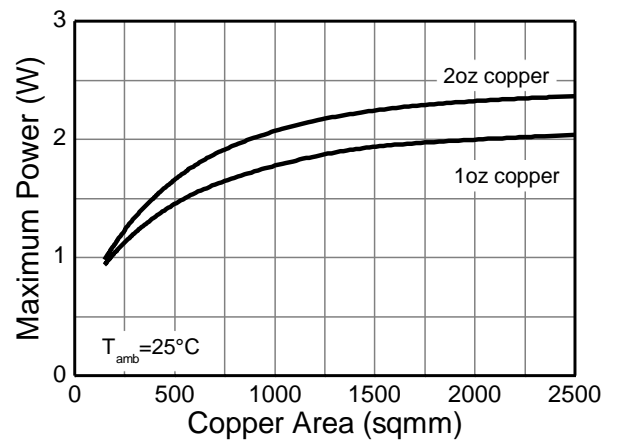
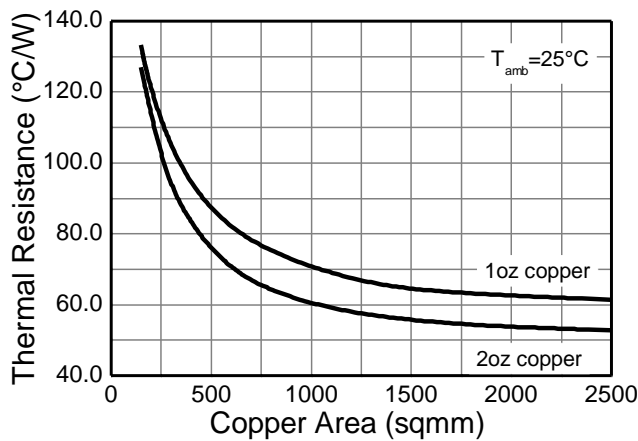
**Derating Curve**



**Transient Thermal Impedance**



**Pulse Power Dissipation**

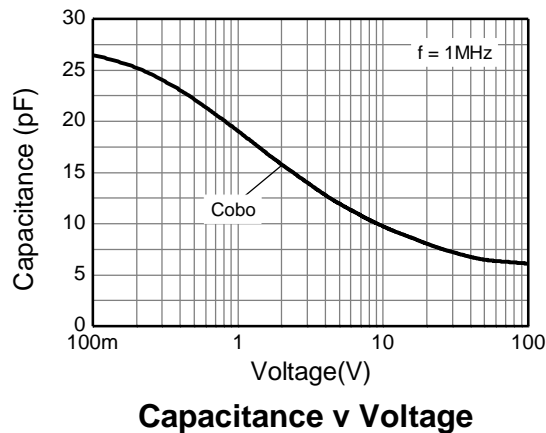
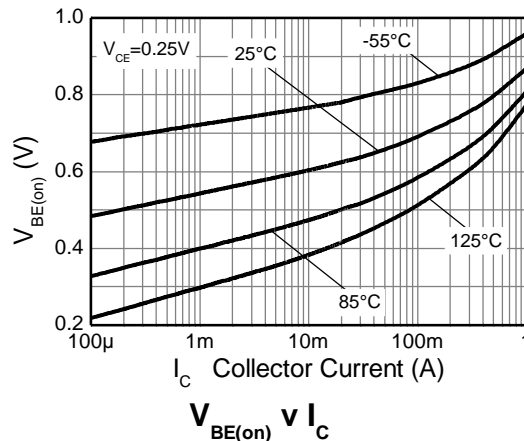
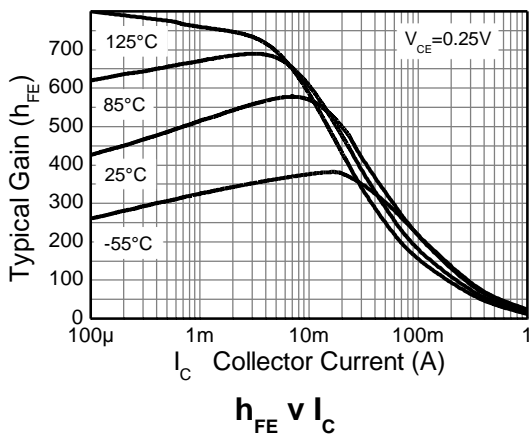


**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$  unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Emitter Breakdown Voltage (Note 11)	$BV_{CEO}$	150	175	-	V	$I_C = 10\text{mA}$
Collector-Base Breakdown Voltage	$BV_{CBO}$	200	310	-	V	$I_C = 100\mu\text{A}$
Collector Cut-Off Current	$I_{CBO}$	-	<1	50	nA	$V_{CB} = 150\text{V}$
Collector Cut-Off Current	$I_{CES}$	-	<1	50	nA	$V_{CE} = 150\text{V}$
Emitter Cut-Off Current	$I_{EBO}$	-	<1	50	nA	$V_{EB} = 7\text{V}$
Static Forward Current Transfer Ratio (Note 11)	$h_{FE}$	200 60 100	- - -	- - -	-	$I_C = 30\text{mA}, V_{CE} = 5\text{V}$ $I_C = 85\text{mA}, V_{CE} = 0.20\text{V}$ $I_C = 150\text{mA}, V_{CE} = 0.25\text{V}$
Base-Emitter Turn-On Voltage (Note 11)	$V_{BE(on)}$	-	0.71	0.95	V	$I_C = 150\text{mA}, V_{CE} = 0.25\text{V}$
Collector-Emitter Saturation Voltage (Note 11)	$V_{CE(sat)}$	-	-	0.25	V	$I_C = 100\text{mA}, I_B = 5\text{mA}$
Delay Time	$t(d)$	-	512	-	ns	$V_{CC} = 120\text{V}, I_C = 150\text{mA},$ $-I_{B2} = 1.5\text{mA}, V_{CE(ON)} = 0.25\text{V}$
Rise Time	$t(r)$	-	426	-	ns	
Storage Time	$t(s)$	-	3413	-	ns	
Fall Time	$t(f)$	-	321	-	ns	
Storage Time	$t(s)$	-	65	-	ns	$V_{CC} = 120\text{V}, I_C = 150\text{mA},$ $-I_{B2} = 1.5\text{mA}, V_{CE(ON)} = 4\text{V}$
Fall Time	$t(f)$	-	294	-	ns	

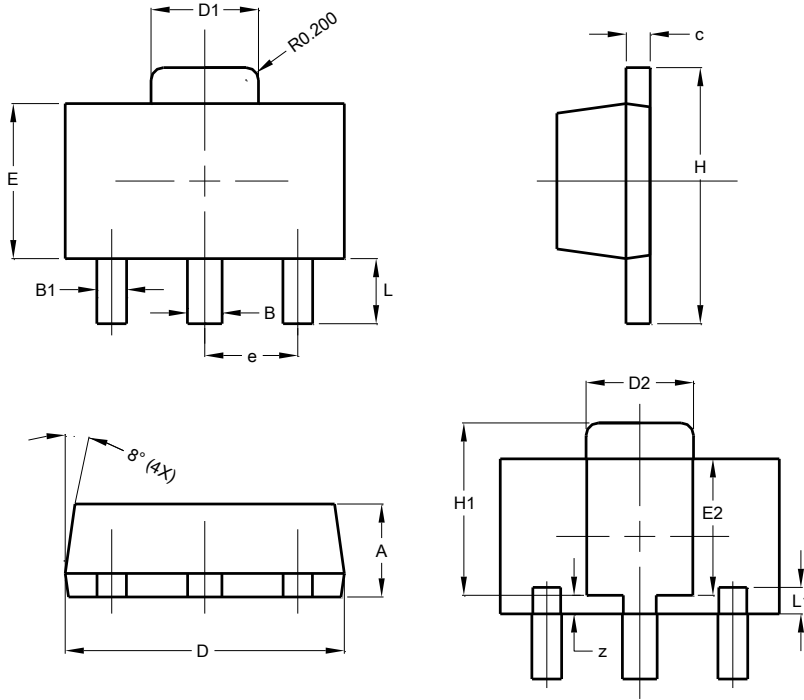
Note: 11. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$  unless otherwise specified.)



**Package Outline Dimensions**

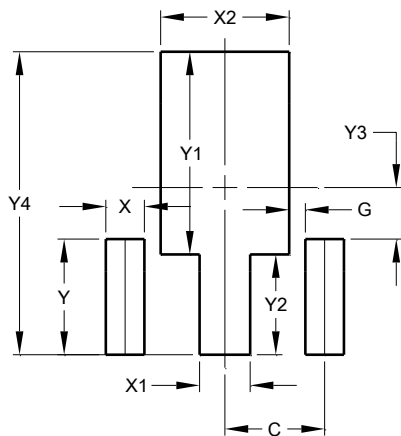
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT89			
Dim	Min	Max	Typ
A	1.40	1.60	1.50
B	0.50	0.62	0.56
B1	0.42	0.54	0.48
c	0.35	0.43	0.38
D	4.40	4.60	4.50
D1	1.62	1.83	1.733
D2	1.61	1.81	1.71
E	2.40	2.60	2.50
E2	2.05	2.35	2.20
e	-	-	1.50
H	3.95	4.25	4.10
H1	2.63	2.93	2.78
L	0.90	1.20	1.05
L1	0.327	0.527	0.427
z	0.20	0.40	0.30
All Dimensions in mm			

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	1.500
G	0.244
X	0.580
X1	0.760
X2	1.933
Y	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.

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